

FORM PTO-1449 U.S. Department of Commerce  
Patent and Trademark Office

Attorney Docket Number:  
5308-156

Serial No.:  
09/911,995

LIST OF DOCUMENTS CITED BY APPLICANT

(Use several sheets if necessary)

Applicants: Ryu et al.

Filing Date: July 24, 2001

Group:  
2811

U. S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
<i>GMH</i>	1	6,767,843	07/27/04	Lipkin et al.	438	758	
	2	6,759,684	07/06/04	Fukuda et al.	257	77	
	3	6,653,659	11/25/03	Ryu et al.	257	77	
	4	6,551,865	04/22/03	Kumar et al.	438	137	
	5	6,429,041	08/06/02	Ryu et al.	438	105	
	6	6,303,508	10/16/01	Alok	438	705	
	7	6,297,100	10/02/01	Kumar et al.	438	268	
	8	6,180,958	01/30/01	Cooper, Jr.	257	77	
	9	6,133,587	10/17/00	Takeuchi et al.	257	77	
	10	6,025,233	02/15/00	Teresawa	438	270	
	11	6,020,600	02/01/00	Miyajima et al.	257	76	
	12	5,976,936	11/02/99	Miyajima et al.	438	268	
	13	5,917,203	06/29/99	Bhatnagar et al.	257	139	
	14	5,877,041	03/02/99	Fuller	438	105	
	15	5,851,908	12/22/98	Harris et al.	438	520	
	16	5,837,572	11/17/98	Gardner et al.	438	199	
	17	5,814,859	09/29/98	Ghezze et al.	257	335	
	18	5,804,483	09/08/98	Harris	438	268	
	19	5,734,180	03/31/98	Malhi	257	77	
	20	5,710,059	01/20/98	Rottner	437	151	
	21	5,629,531	05/13/97	Palmour	257	77	
	22	5,510,281	04/23/96	Ghezze et al.	437	41	
	23	5,396,085	03/07/95	Baliga	257	77	
	24	5,393,999	02/28/95	Malhi	257	289	
	25	5,385,855	01/31/95	Brown et al.	437	41	
<i>GMH</i>	26	5,384,270	01/24/95	Ueno	437	40	

EXAMINER  
EXAMINER

*G. Munson*

DATE CONSIDERED *8 July 2005*

Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>FORM PTO-1449 U.S. Department of Commerce</b> Patent and Trademark Office				<b>Attorney Docket Number:</b> 5308-156		<b>Serial No.:</b> 09/911,995	
<b>LIST OF DOCUMENTS CITED BY APPLICANT</b> (Use several sheets if necessary)							
				Applicants: Ryu et al.			
				Filing Date: July 24, 2001		Group: 2811	
<i>27</i>	27	5,348,895	09/20/94	Smayling et al.	437	54	
<i>28</i>	28	5,270,554	12/14/93	Palmour	257	77	
<i>29</i>	29	5,111,253	05/05/92	Korman et al.	257	341	
<i>30</i>	30	4,811,065	03/07/89	Cogan	257	328	
<i>31</i>	31	3,629,011	12/21/71	Tohi et al.	148	1.5	
<i>32</i>	32	2004/0212011	10/28/04	Ryu	257	335	
<i>33</i>	33	2004/0211980 A1	10/28/04	Ryu	257	200	
<i>34</i>	34	2002/0030191	03/14/02	Das et al.	257	77	
<i>35</i>	35	<del>2002/0047125 A1</del> 6,759,684	<del>04/25/02</del> 02/06/04	Fukuda et al.	257	77	
<i>36</i>	36	2002/0102358	08/01/02	Das et al.	472	377	
<i>37</i>	37	6,137,139	10/24/00	Zang et al	257	372	
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class -	Subclass	Translation Yes   No
<i>37</i>	37	DE 19832329 A1	02/04/98	Germany			
<i>38</i>	38	EP 1 204 145 A2	08/05/02	EPO			
<i>39</i>	39	EP 1 058 317 A2	12/06/00	EPO			
<i>40</i>	40	JP 01117363	05/10/89	Japan			Abstract
<i>41</i>	41	JP 03034466	02/14/91	Japan			Abstract
<i>42</i>	42	WO 97/98754	03/06/97	PCT			
<i>43</i>	43	WO 98/02916	01/22/98	PCT			
<i>44</i>	44	WO 01/78134 A1	10/18/01	PCT			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
<i>45</i>	45	Baliga, Power Semiconductor Devices, Chapter 7, PWS Publishing, 1996					
<i>46</i>	46	Bhatnagar et al. "Comparison of 6H-SiC, 3C-SiC, and Si for Power Devices," <i>IEEE Transactions on Electron Devices</i> , Vol. 40, No. 3, March 1993, pp. 645-55.					
<i>47</i>	47	Chung et al., "The Effect of Si:C Source Ratio on SiO <sub>2</sub> /SiC Interface State Density for Nitrogen Doped 4H and 6H-SiC," <i>Materials Science Forum</i> . (2000) Vols. 338-342, pp. 1097-1100.					
<i>48</i>	48	Dahlquist et al. "A 2.8kV, Forward Drop JBS Diode with Low Leakage," <i>Materials Science Forum</i> , Vols. 338-342, (2000) pp. 1179-82.					

already of record 8/24/04

consider via correspond  
as 6,137,139EXAMINER  
EXAMINERG. MUNSONDATE CONSIDERED 8 July 2005

Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office		Attorney Docket Number: 5308-156	Serial No.: 09/911,995
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)			
		Applicants: Ryu et al.	
		Filing Date: July 24, 2001	Group: 2811
<i>2/10/01</i>	49	Mondal et al. "An Integrated 500-V Power DSMOSFET/Antiparallel Rectifier Device with Improved Diode Reverse Recovery Characteristics," <i>IEEE Electron Device Letters</i> , Vol. 23, No. 9, September 2002, pp. 562-4.	
	50	Motorola Power MOSFET Transistor Databook, 4th edition. Motorola, Inc., 1989, pp. 2-5-4 - 2-5-7.	
	51	Palmour et al. "SiC Device Technology: Remaining Issues," <i>Diamond and Related Materials</i> , vol. 6, 1997, pp. 1400-1404.	
	52	Rao et al. "P-N Junction Formation in 6H-SiC by Acceptor Implantation into N-Type Substrate," <i>Nuclear Instruments and Methods in Physics Research B</i> , vol. 106, 1995, pp. 333-338.	
	53	Rao et al. "Al and N Ion Implantations in 6H-SiC," <i>Silicon Carbide and Related Materials</i> , 1995 Conf, Kyoto, Japan. Published 1996.	
	54	Capano, M.A., et al., Ionization Energies and Electron Mobilities in Phosphorus--and Nitrogen-Implanted 4H-Silicon Carbide, IEEE ICSCRM Conference 1999, Research Triangle Park, North Carolina (Oct. 10-13, 1999).	
	55	Patel, R., et al., Phosphorus-Implanted High-Voltage N.sup.+ P 4H-SiC Junction Rectifiers, <i>Proceedings of 1998 International Symposium on Power Semiconductor Devices &amp; ICs</i> , pp. 387-390 (Kyoto).	
<i>2/10/01</i>	56	Dastidar, Sujoyita, A Study of P-Type Activation in Silicon Carbide, Thesis (Purdue University, May 1998).	

EXAMINER  
EXAMINERG. MUNSONDATE CONSIDERED 8 JULY 2003

Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.